

Part Number: L-799SURKMGKW

Hyper Red
Mega Green

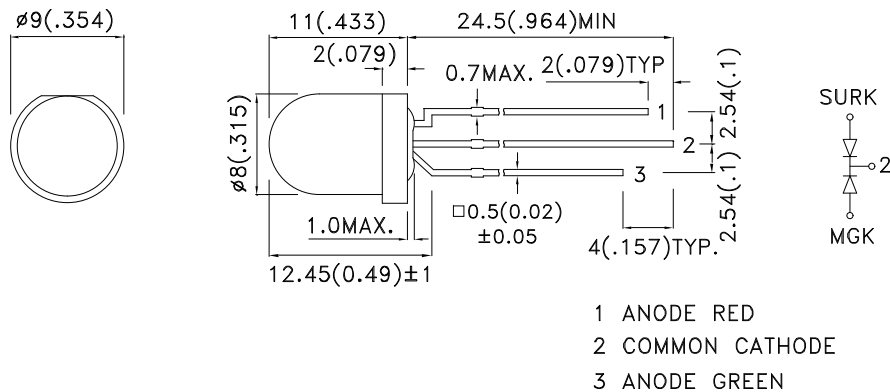
Features

- UNIFORM LIGHT OUTPUT.
- LOW POWER CONSUMPTION.
- MILKY WHITE DIFFUSION LENS.
- 3 LEADS WITH ONE COMMON LEAD.
- I.C. COMPATIBLE.
- LONG LIFE - SOLID STATE RELIABILITY.
- RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with InGaAlP on GaAs substrate Light Emitting Diode.
The Mega Green source color devices are made with InGaAlP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Lead spacing is measured where the lead emerge from the package.
4. Specifications are subject to change without notice.



Selection Guide

| Part No. | Dice | Lens Type | Iv (mcd) [2] @ 20mA | | Viewing Angle [1] |
|---------------|----------------------|----------------|------------------------|------|----------------------|
| | | | Min. | Typ. | 2θ1/2 |
| L-799SURKMGKW | Hyper Red (InGaAlP) | WHITE DIFFUSED | 380 | 600 | 50° |
| | Mega Green (InGaAlP) | | 50 | 130 | |

Notes:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.
2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

| Symbol | Parameter | Device | Typ. | Max. | Units | Test Conditions |
|-----------------------|--------------------------|-------------------------|-------------|------------|-------|---------------------------|
| λ_{peak} | Peak Wavelength | Hyper Red Mega Green | 650 574 | | nm | I _F =20mA |
| λ_D [1] | Dominant Wavelength | Hyper Red Mega Green | 635 570 | | nm | I _F =20mA |
| $\Delta\lambda_{1/2}$ | Spectral Line Half-width | Hyper Red Mega Green | 28 20 | | nm | I _F =20mA |
| C | Capacitance | Hyper Red Mega Green | 35 15 | | pF | V _F =0V;f=1MHz |
| V _F [2] | Forward Voltage | Hyper Red Mega Green | 1.95 2.1 | 2.5 2.5 | V | I _F =20mA |
| I _R | Reverse Current | Hyper Red Mega Green | | 10 10 | uA | V _R = 5V |

Notes:

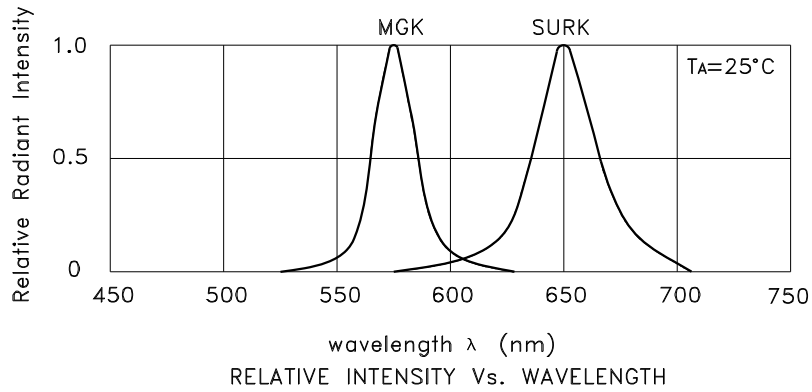
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

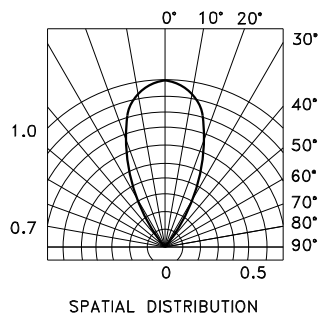
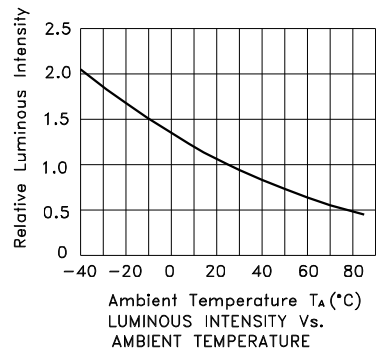
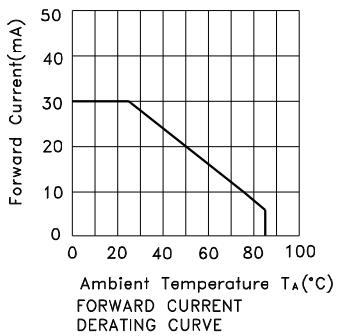
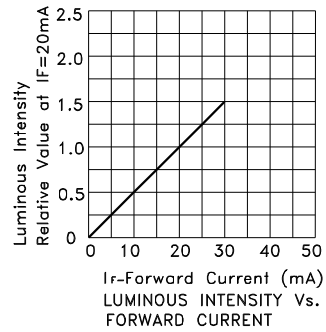
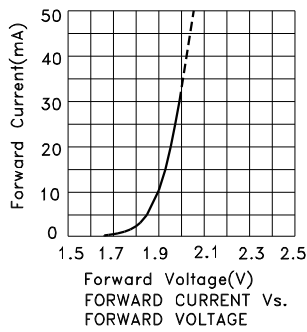
| Parameter | Hyper Red | Mega Green | Units |
|---------------------------------|---------------------|------------|-------|
| Power dissipation | 75 | 75 | mW |
| DC Forward Current | 30 | 30 | mA |
| Peak Forward Current [1] | 185 | 150 | mA |
| Reverse Voltage | 5 | | V |
| Operating / Storage Temperature | -40°C To +85°C | | |
| Lead Solder Temperature [2] | 260°C For 3 Seconds | | |
| Lead Solder Temperature [3] | 260°C For 5 Seconds | | |

Notes:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. 2mm below package base.
3. 5mm below package base.

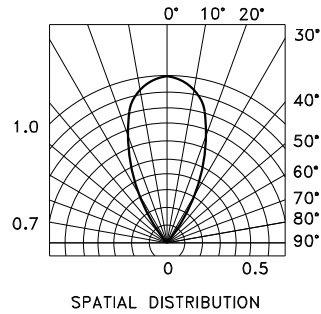
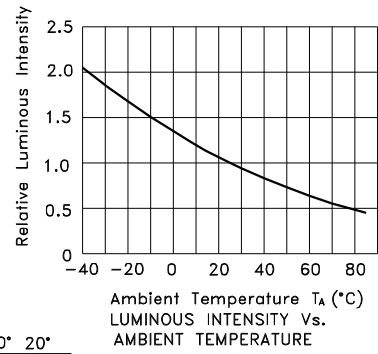
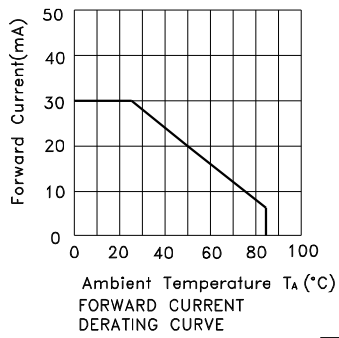
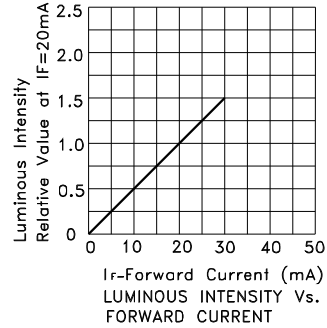
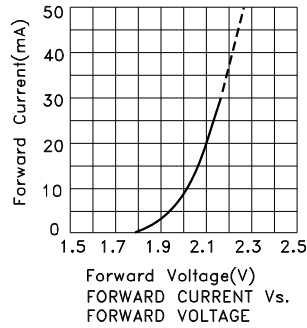


L-799SURKMGKW Hyper Red



Kingbright

Mega Green



LED MOUNTING METHOD

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures.

(Fig. 1)



Fig.1

“○” Correct mounting method “X” Incorrect mounting method

Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit.

(Fig. 2)



Fig. 2

3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.

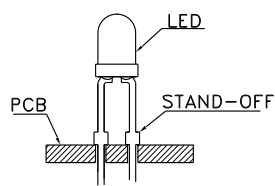


Fig. 3

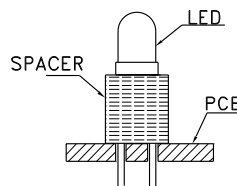


Fig. 4

LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



Fig. 5



Fig. 6

2. Lead forming or bending must be performed before soldering, never during or after Soldering.
3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
5. Do not bend the leads more than twice. (Fig. 8)

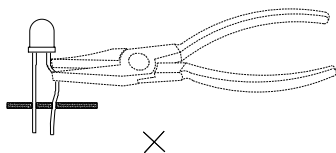


Fig. 7



Fig. 8

6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.



Fig. 9